



UCSC Electron-Ion Collider plans

Simone M. Mazza on behalf of SCIPP UCSC group

Simone Michele Mazza – UCSC EIC plans

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Physics interests

- Exploring simulation topics, in conversation with LANL EIC group
 - Simulations to identify detector demands
 - Geared towards the definition of detector requirements and the motivation for increased 4D precision
- Development of detector reconstruction techniques
 - e.g.: c-tagging algorithms
- Particle Physics topics such as Heavy Flavor Physics are a natural fit
 - D*-meson CP violation
 - BSM searches (e.g.: leptoquarks)
- Also interest in nuclear structure & behavior

Activities - Sensors

- Sensors (A. Seiden, H. Sadrozinski, B. Schumm, 1 FTE post-doc(me), ½ FTE tech, students)
- Testing FBK AC-LGAD with IR laser with the goal to define a design of a baseline detector
 - Sensor characterization, hit reconstruction algorithms.
 - Front and back IR laser study on etched AC-LGADs (Also prospect of etching at BNL)
 - Geometry optimization (pad pitch/size) and parameter optimization (N+ layer resistivity, Oxide thickness...)
- AC-LGAD simulation with TCAD softwares Sentaurus and Silvaco.
- Support to TB runs (at FNAL)
- Prepare a submission with FBK to manufacture thin AC-LGAD (35-20um thickness)
- Started collaboration with KEK for AC-LGAD production at HPK

CH0 POS Chi2 1000 900 0.9 650 800 0.8 **Reco hit** 700 0.7 600 Fractional charge 600 0.6 550 500 0.5 for Ch1 400 0.4 10 500 0.3 300 450 200 0.2 100 100 200 300 400 500 600 700 800 900 1000 300 350 400 450 500 550 600 650 Simone Michele Mazza - SCIPP UCSC

Fractional charge sharing based event reconstruction

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Activities - Readout

- ASICs (R. Johnson, 1/2 FTE designer, students)
 - In recognition of the need for a low-noise, ultra-fast readout ASIC with pitch < 500um with acceptable power dissipation
- Work on specifications and simulations
 - Including definition of front-end
- Support two SBIR proposals for ASIC development
 - One for SiGe front-end
 - The other for 65 nm CMOS readout including back-end
- Assembly and test of resulting 16ch chip (sensor plus readout)

Infrastructures at UCSC

- Clean room with automatic wire-bonders
- Sensor-board assembly capabilities
- Probe stations with possibility of cold measurements
- Power supply, parameter analyzer, LCR meter
- 2,4,13 Ghz Oscilloscopes for readout
- Setup for testing fast readout electronics
- Several single and multi-channel general purpose amplifier boards for single a array dices
- Laser TCT (200ps width) with cold chuck
- Beta source charge collection setup in climate chamber with fast time reference
- TCAD, Silvaco, Sentaurus and Cadence software







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